



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Product Description

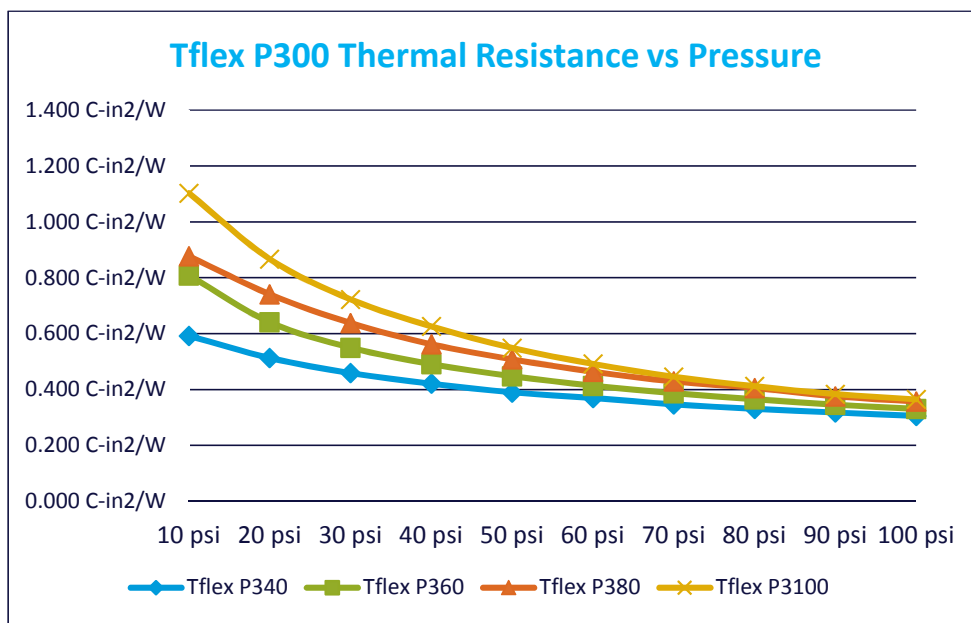
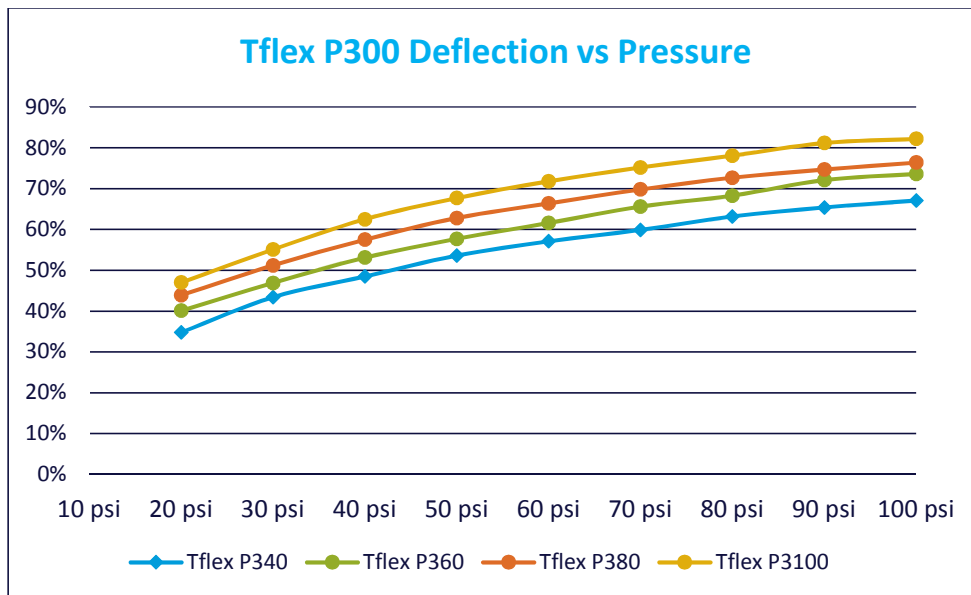
Laird Tflex® P300 is a soft and compliant gap filler with an integrated polyimide liner. Laird has leveraged its vast experience and knowledge in the development of thermally conductive materials to develop a soft and compliant gap filler that minimizes contact resistance and board level stresses. In conjunction with these key traits Laird understands that not all applications are the same. As a result, Tflex P300 comes with a unique and integrated polyimide film on one side. This liner provides numerous application benefits like electrical isolation, placement ease during assembly, and tear resistance for applications that require shear.

FEATURES AND BENEFITS

- Compliant nature minimizes contact resistance
- Integrated polyimide film provides dielectric strength
- Resistance to burrs and mechanical forces
- Resistant to shear forces.
- Thermal Conductivity of 3 W/mK
- Contrasting color allows integration with vision system
- Low silicone bleed

SPECIFICATIONS

TYPICAL PROPERTIES	VALUE	TEST METHOD
Construction & Composition	Polyimide lined elastomer	N/A
Color	Purple	Visual
Thickness Range	0.50mm (0.020") 5.0mm (0.20")	N/A
Thickness Tolerance	+/- 10%	N/A
Thermal Conductivity (W/mK)	3.0	ASTM D5470
Density (g/cc)	3.10	Helium Pycnometer
Hardness (Shore 00)	30	ASTM D2240
Outgassing TML (weight %)	0.2	ASTM E595
Outgassing CVCN (weight %)	0.05	ASTM E595
Temperature Range	-40°C to 125°C	Laird Test Method
Rth@ 40 mils, 10 psi	0.592 °C-in ² /W	ASTM D5470 (Modified)
Dielectric Constant @ 1 MHz	4.6	ASTM D150
UL Flammability Rating	V-0	UL-94
Volume Resistivity	2 x 10 ¹⁴ ohm-cm	ASTM D257
Breakdown Voltage	>5KV	ASTM D149



AVAILABILITY

STANDARD THICKNESSES

- 0.5mm (0.020") to 5.0mm (0.200") thick material available in 0.25mm (0.010") increments
- Available in standard sheet sizes of 18" x 18" and 9" x 9" or custom die cut parts

PART NUMBER SYSTEM

Tflex™ indicates Laird elastomeric thermal gap filler product line. P3xxx indicates Tflex P300 product line with thickness in mils (0.001")

EXAMPLES:

- Tflex™ P340 = 0.040" thick Tflex™ P300 material

A17801-00 Tflex P300 DS 110317

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2015 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.